



PCN# : P4C9AAB
Issue Date : Mar. 02, 2015

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : May. 31, 2015

Expected First Date Code of Changed Product :1519

Description of Change (From) :

SDIP/DIP packages under the following assembly sites using non green mold compound and SDIP package only qualified with IR reflow precondition.

Mfg site/Subcon	Package	Mold Compound change from	Qual Plan
FSC China Subcontractor A	SDIP/DIP	ELL2KS400	Q20140354
FSC China Subcontractor B	SDIP/DIP	EME1200D	Q20140354

Description of Change (To) :

Products assembled in the SDIP/DIP packages using the green Mold Compound as shown below and SDIP package had been qualified with both IR reflow and wave soldering precondition.

Mfg site/Subcon	Package	Mold Compound change to	Qual Plan
FSC China Subcontractor A	SDIP/DIP	ELER-8-640	Q20140354
FSC China Subcontractor B	SDIP/DIP	EK1800G	Q20140354

Reason for Change:

This is a change to mold compounds used for Fairchild products assembled in SDIP/DIP packages and the package SDIP has been successfully qualified with wave soldering precondition. The qualified green Mold Compounds are low halogen material with improved thermal & mechanical properties. There are no changes to the currently approved assembly facilities or any other materials used to produce these products. Package outline drawings of the affected

products remain un-changed. Affected products will be fully compliant to all published data sheet specifications. Quality and reliability will remain at the highest standards already demonstrated with Fairchild's existing SDIP/DIP products. If you require data or samples to evaluate this change, please contact Fairchild Semiconductor within 30 days of receipt of this notification.

Affected Product(s): Please refer to the list of affected products in the addendum attached in the PCN email you received. This list is based on an analysis of your company's procurement history.

Qualification Plan	Device	Package	Process	No. of Lots
Q20140354	DF10S	SDIP	GPP	6

Test Description:	Condition:	Standard :	Duration:	Results:
Temperature Humidity Bias Test	85%RH, 85C, 80% BV	JESD22-A101B	1000 hrs	0/154
High Temperature Reverse Bias Test	150C, 80% BV	JESD22-A108	1000 hrs	0/308
Highly Accelerated Stress Test	130C,85%RH,42V	JESD22-A110	96hrs	0/308
Power Cycle	Delta 100C, 5 Min cycle	MIL-STD-750-1036	6000 cycles	0/231
Power Cycle	Delta 100C, 3.5 Min cycle	MIL-STD-750-1036	8572 cycles	0/77
Temperature Cycle	-55C, 150C	JESD22-A104	1000cycles	0/462

Qualification Plan	Device	Package	Process	No. of Lots
Q20140354	DF08S	SDIP	GPP	2

Test Description:	Condition:	Standard :	Duration:	Results:
Highly Accelerated Stress Test	130C,85%RH,42V	JESD22-A110	96hrs	0/154
Temperature Cycle	-55C, 150C	JESD22-A104	1000 cycles	0/154